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OvationONS II Family Performance Table

Parameter	CYONS2000	CYONS2001	CYONS2100	CYONS2101	CYONS2110	Unit
Variable resolution	400, 800, 1600	400, 800, 1600	400–3200	400–3200	400–3200	CPI
Maximum speed	30	30	75	75	75	in/s
Maximum acceleration	20	20	30	30	30	g
Integrated MCU	Yes	Yes	Yes	Yes	Yes	
CapSense®	No	No	No	No	26 inputs	
Flash	16	16	32	32	32	KB
SRAM	2	2	2	2	2	KB
Interfaces	Full-speed USB 4-wire SPI up to 28 GPIOs	4-wire SPI up to 28 GPIOs	Full-speed USB 4-wire SPI up to 28 GPIO	4-wire SPI up to 28 GPIOs	Full-speed USB 4 wire SPI up to 28 GPIOs	
Battery supply voltage	NA	0.8 to 3.6	NA	0.8 to 3.6	0.8 to 3.6	V
USB supply voltage	4.25 to 5.25	NA	4.25 to 5.25	NA	4.25 to 5.25	V
External supply voltage	2.7 to 3.6	2.7 to 3.6	2.7 to 3.6	2.7 to 3.6	2.7 to 3.6	V
Zero motion	1	1	1	1	1	count

OvationONS II Family Applications

- Wired and wireless laser mice
 - Gaming, graphic design, desktop, and mobile mice
- Optical trackballs
- Battery powered devices
- Motion sensing applications

OvationONS II Family Functional Description

The OvationONS II family is a two-piece laser navigation SoC kit containing the integrated IC package and the molded lens.

The 2 kV ESD rated IC package integrates the VCSEL and laser sensor SoC. Depending on the product selected, the SoC includes an MCU, flash, SRAM, two internal oscillators, CapSense system, battery boost regulator, power regulator, and full-speed USB.

The molded lens collimates the VCSEL beam and images the light scattered from the tracking surface onto the sensor portion of the laser detector. The lens has features for registration to the package and easily snaps to the PC board.

At the heart of the system is the OptiCheck laser navigation engine. It supports all functions required for tracking, including laser power control, resolution control, and self-adjusting power reduction, which reduces power consumption when motion stops. The laser output power is pre-calibrated to meet the eye safety requirements of IEC 60825 Class 1.

The navigation engine is accessed and controlled by an integrated PSoC-based MCU. The interface between the two blocks is through a system bus and a collection of navigation engine interrupts. Full details are available in the [OvationONS II Laser Navigation System-on-Chip TRM \(Technical Reference Manual\)](#) or in the PSoC Designer integrated development environment (IDE) software.

In addition to controlling the navigation engine, the PSoC MCU also serves as the main application processor. Based on Cypress's M8C architecture, the PSoC supports a rich instruction set, multiple processor speeds, and flexible GPIOs. Its internal main oscillator requires no external crystal. On-chip flash and RAM allow entire navigation systems to be implemented with the single SoC.

The OvationONS II family supports a wide range of powering options. Internal regulators minimize the need for external circuitry. Depending on the product selected, the device can be powered from a USB 5 V supply, from a single battery, from dual batteries, or from an external supply. The configuration and use of the power blocks are controlled with the integrated PSoC.

Wired sensors include an integrated full-speed USB. As with the navigation engine and power system, the USB block is controlled by the integrated PSoC.

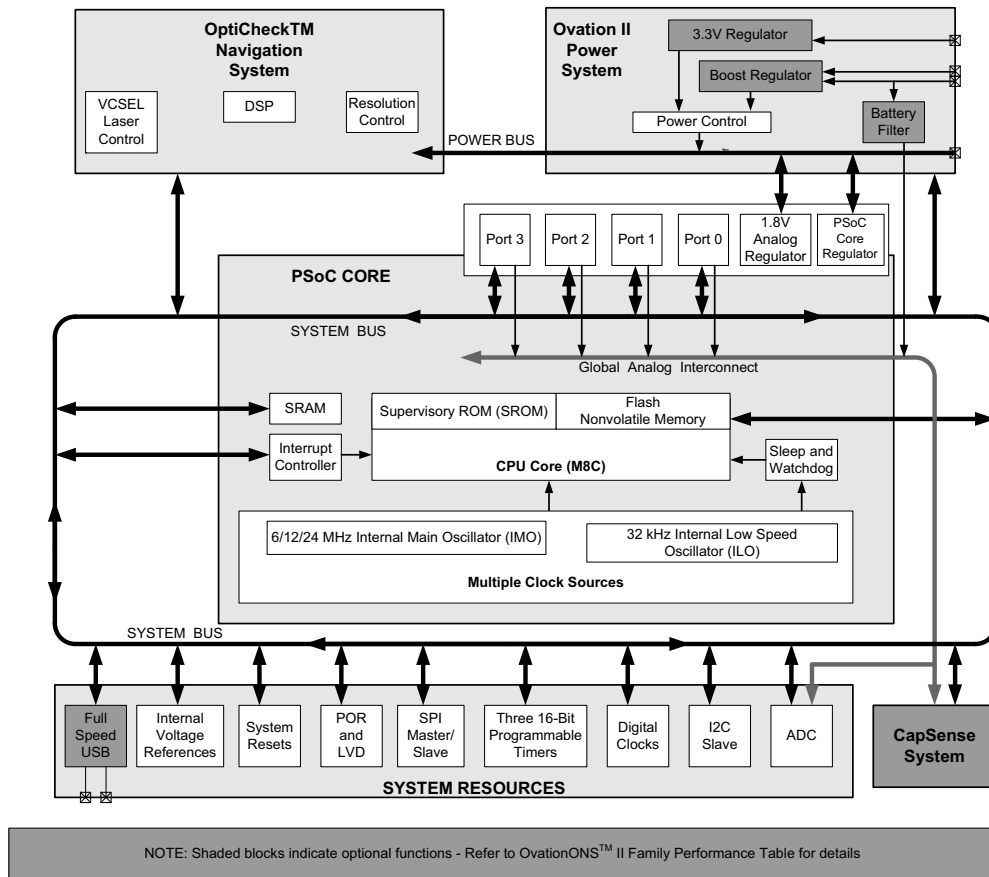
All sensors support a 4-wire SPI interface. A typical use of the SPI interface is to provide access to a radio for wireless applications. An I²C interface is also included with all devices.

The CYONS2110 device also supports CapSense functions, allowing additional features and differentiation in end products.

All features of the OvationONS II family are configured using Cypress's PSoC Designer™ software, allowing fast application development and time to market.

The OvationONS II family block diagram is shown on [Figure 2](#) on page 4. It shows a true SoC solution that enables design cycle reductions along with savings on manufacturing, PCB area, and component inventory management. The packaged solution delivers a fully integrated system that demonstrates tracking performance with efficient power consumption.

Figure 2. Block Diagram



Pin Description

This section describes, lists, and illustrates the CYONS2000 device pins and pinout configurations. The CYONS2000 is available in a 42-pin quad flat no-leads (QFN) package.

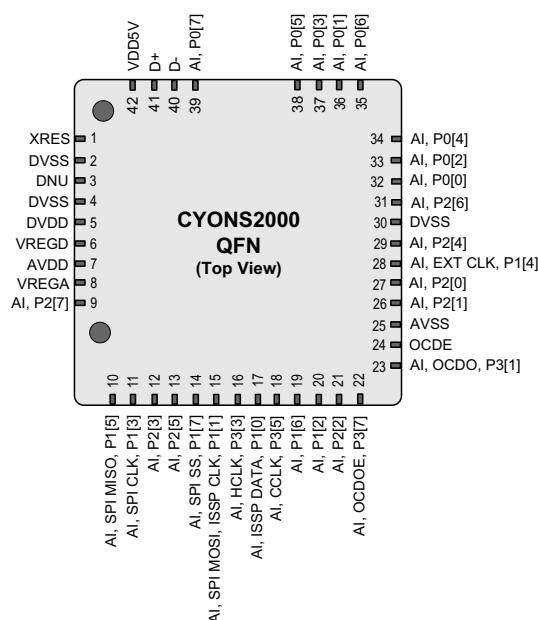
Table 1. CYONS2000 Pin Description

Pin	Name	Digital	Analog	Description
1	XRES	I		Active high external reset with internal pull-down
2	DVSS	Power	Power	Digital ground
3	DNU			Do not use
4	DVSS	Power	Power	Digital ground
5	DVDD	Power	Power	Digital supply voltage and regulated output (see Power Supply Connections on page 11)
6	VREGD	Power	Power	Digital VREG
7	AVDD	Power	Power	Analog supply voltage
8	VREGA	Power	Power	Analog VREG
9	P2[7]	I/O	I	GPIO port 2 pin 7
10	P1[5]	IOHR	I	SPI MISO, I2C_SDA, GPIO port 1 pin 5
11	P1[3]	IOHR	I	SPI CLK, GPIO port 1 pin 3
12	P2[3]	I/O	I	GPIO port 2 pin 3
13	P2[5]	I/O	I	GPIO port 2 pin 5
14	P1[7]	IOHR	I	SPI SS, I2C_SCL, GPIO port 1 pin 7
15	P1[1]	IOHR	I	SPI MOSI, ISSP CLK ^[1] , I2C_SCL, GPIO port 1 pin 1
16	P3[3]	IOHR	I	HCLK (OCD high speed clock output), GPIO port 3 pin 3
17	P1[0]	I/O	I	ISSP DATA ^[1] , I2C_SDA, GPIO port 1 pin 0
18	P3[5]	I/O	I	CCLK (OCD CPU clock output), GPIO port 3 pin 5
19	P1[6]	IOHR	I	GPIO port 1 pin 6
20	P1[2]	IOHR	I	GPIO port 1 pin 2
21	P2[2]	I/O	I	GPIO port 2 pin 2
22	P3[7]	I/O	I	OCDOE (OCD mode direction pin), GPIO port 3 pin 7
23	P3[1]	I/O	I	OCDO (OCD odd data output), GPIO port 3 pin 1
24	OCDE	OCD	OCD	OCDE (OCD even data output)
25	AVSS	Power	Power	Analog ground
26	P2[1]	I/O	I	GPIO port 2 pin 1
27	P2[0]	I/O	I	GPIO port 2 pin 0
28	P1[4]	IOHR	I	EXT CLK, GPIO port 1 pin 4
29	P2[4]	I/O	I	GPIO port 2 pin 4
30	DVSS	Power	Power	Digital ground
31	P2[6]	I/O	I	GPIO port 2 pin 6
32	P0[0]	I/O	I	GPIO port 0 pin 0
33	P0[2]	I/O	I	GPIO port 0 pin 2
34	P0[4]	I/O	I	GPIO port 0 pin 4
35	P0[6]	I/O	I	GPIO port 0 pin 6
36	P0[1]	I/O	I	GPIO port 0 pin 1

Table 1. CYONS2000 Pin Description (continued)

Pin	Name	Digital	Analog	Description
37	P0[3]	I/O	I	GPIO port 0 pin 3
38	P0[5]	I/O	I	GPIO port 0 pin 5
39	P0[7]	I/O	I	GPIO port 0 pin 7
40	D-	I/O		USB data
41	D+	I/O		USB data
42	VDD5V	Power	Power	5-V power
CP	DVSS	Power	Power	Center pad (CP) must be connected to digital ground

Legend: I=Input; O=Output; H=5 mA High Output Drive, R=Regulated Output, OCD = On-Chip-Debug

Figure 3. Pin Diagram

Note

- These are the in-system serial programming (ISSP) pins. Unlike other GPIOs, they are not high impedance at power on reset (POR). See the [Technical Reference Manual \(TRM\)](#) or in the PSoC Designer development software for more details.

Microcontroller System

Features

- Powerful Harvard-architecture processor
 - M8C processor speed up to 24 MHz
 - Low power at high speed
 - Interrupt controller
 - Operating temperature range: +5 °C to +45 °C
- Flexible on-chip memory
 - 16 KB flash program storage
50,000 erase and write cycles
 - 2 KB SRAM data storage
 - Partial flash updates
 - Flexible protection modes
 - In-system serial programming (ISSP)
- Full-speed USB (12 Mbps)
 - Eight unidirectional endpoints
 - One bidirectional control endpoint
 - USB 2.0 compliant
 - Dedicated 512-byte buffer
 - Internal 3.3-V output regulator
- Complete development tools
 - Free development tool (PSoC Designer)
 - Full featured in-circuit emulator (ICE) and programmer
 - Full speed emulation
 - Complex breakpoint structure
 - 128 KB trace memory
- Precision programmable clocking
 - Internal $\pm 5.0\%$ 6-, 12-, 24-MHz main oscillator
 - Internal 32-kHz low speed oscillator
 - Supports optional external 32-kHz crystal
 - 0.25% accuracy for USB with no external crystal
- Programmable pin configurations
 - 25-mA sink current on all GPIOs
 - Pull-up, high-Z, open drain, or strong drive modes on all GPIOs
 - Up to 28 analog inputs on GPIO
 - Configurable inputs on all GPIOs
 - Selectable, regulated digital I/O on port 1
 - 3.3-, 2.5-, or 1.8-V output
 - 3.0 V, 20 mA total port 1 source current
 - 5-mA source current mode on ports 0 and 1
 - Hot swap capable
- Versatile analog mux
 - Common internal analog bus
 - Simultaneous connection of I/O combinations
 - High power supply rejection ratio (PSRR) comparator
 - Low dropout voltage regulator for the analog array
- Additional system resources
 - SPI master and SPI slave
 - Clock speed up to 12 MHz
 - Three 16-bit timers
 - Watchdog and sleep timers
 - Internal voltage reference
 - Integrated supervisory circuit
 - Analog-to-digital converter (ADC)
 - I²C slave

PSoC Functional Overview

Cypress's PSoC on-chip controllers combine dynamic, configurable analog and digital blocks and an 8-bit MCU on a single chip, replacing multiple discrete components while delivering optimal flexibility and advanced functionality. A PSoC device includes configurable analog and digital blocks, and programmable interconnect. This architecture enables the creation of customized peripheral configurations, to match the requirements of each individual application. Additionally, a fast CPU, Flash program memory, SRAM data memory, and configurable I/O are included in a range of convenient pinouts.

The architecture for this device family, as illustrated in the [Block Diagram](#) on page 4, contains: the core, the navigation sensor, the power system, and the system resources (including a full-speed USB port). A common, versatile bus enables connection between I/O and the analog system. GPIO is also included. The GPIO provides access to the MCU and analog mux.

The PSoC Core

The PSoC core is a powerful engine that supports a rich instruction set. The PSoC core encompasses SRAM for data storage, an interrupt controller, sleep and watchdog timers, an Internal Main Oscillator (IMO), and an Internal Low Speed Oscillator (ILO). The CPU core, called the M8C, is a powerful processor with speeds up to 24 MHz. The M8C is a 4 MIPS, 8-bit Harvard architecture microprocessor.

System resources provide additional capability, such as configurable USB and SPI master-slave communication interface, three 16-bit programmable timers, and various system resets supported by the M8C.

The Analog Multiplexer System

The analog mux bus connects to every GPIO pin. Pins are connected to the bus individually or in any combination. Analog signals may be routed to an internal analog-to-digital converter.

Other multiplexer applications include:

- Chip-wide mux that enables analog input from any I/O pin
- Crosspoint connection between any I/O pin combinations

Additional System Resources

System resources, some previously listed, provide additional capability useful to complete systems. Additional resources include low-voltage detection (LVD) and power on reset. Brief statements describing the merits of each system resource follow:

- The SPI master/slave module
 - Provides communication over three or four wires
 - Runs at speeds of 46.9 kHz to 3 MHz (lower for a slower system clock).
- An I²C slave module
- Low voltage detection (LVD) interrupts can signal the application of falling voltage levels, while the advanced Power On Reset (POR) circuit eliminates the need for a system supervisor.
- An internal reference provides an absolute reference for capacitive sensing.

Getting Started

For in depth information, along with detailed programming details, see the *PSoC[®] Technical Reference Manual*.

For up-to-date ordering, packaging, and electrical specification information, see the latest [PSoC device datasheets](#) on the web.

Application Notes

[Cypress application notes](#) are an excellent introduction to the wide variety of possible PSoC designs.

Development Kits

[PSoC Development Kits](#) are available online from and through a growing number of regional and global distributors, which include Arrow, Avnet, Digi-Key, Farnell, Future Electronics, and Newark.

Training

[Free PSoC technical training](#) (on demand, webinars, and workshops), which is available online via www.cypress.com, covers a wide variety of topics and skill levels to assist you in your designs.

CYPros Consultants

Certified PSoC Consultants offer everything from technical assistance to completed PSoC designs. To contact or become a PSoC Consultant go to the [CYPros Consultants](#) web site.

Solutions Library

Visit our growing [library of solution focused designs](#). Here you can find various application designs that include firmware and hardware design files that enable you to complete your designs quickly.

Technical Support

[Technical support](#) – including a searchable Knowledge Base articles and technical forums – is also available online. If you cannot find an answer to your question, call our Technical Support hotline at 1-800-541-4736.

Development Tools

PSoC Designer™ is the revolutionary Integrated Design Environment (IDE) that you can use to customize PSoC to meet your specific application requirements. PSoC Designer software accelerates system design and time to market. Develop your applications using a library of precharacterized analog and digital peripherals (called user modules) in a drag-and-drop design environment. Then, customize your design by leveraging the dynamically generated application programming interface (API) libraries of code. Finally, debug and test your designs with the integrated debug environment, including in-circuit emulation and standard software debug features. PSoC Designer includes:

- Application editor graphical user interface (GUI) for device and user module configuration and dynamic reconfiguration
- Extensive user module catalog
- Integrated source-code editor (C and assembly)
- Free C compiler with no size restrictions or time limits
- Built-in debugger
- In-circuit emulation
- Built-in support for communication interfaces:
 - Hardware and software I²C slaves and masters
 - Full-speed USB 2.0
 - Up to four full-duplex universal asynchronous receiver/transmitters (UARTs), SPI master and slave, and wireless

PSoC Designer supports the entire library of PSoC 1 devices and runs on Windows XP, Windows Vista, and Windows 7.

PSoC Designer Software Subsystems

Design Entry

In the chip-level view, choose a base device to work with. Then select different onboard analog and digital components that use the PSoC blocks, which are called user modules. Examples of user modules are analog-to-digital converters (ADCs), digital-to-analog converters (DACs), amplifiers, and filters. Configure the user modules for your chosen application and connect them to each other and to the proper pins. Then generate your project. This prepopulates your project with APIs and libraries that you can use to program your application.

The tool also supports easy development of multiple configurations and dynamic reconfiguration. Dynamic reconfiguration makes it possible to change configurations at run time. In essence, this allows you to use more than 100 percent of PSoC's resources for a given application.

Code Generation Tools

The code generation tools work seamlessly within the PSoC Designer interface and have been tested with a full range of debugging tools. You can develop your design in C, assembly, or a combination of the two.

Assemblers. The assemblers allow you to merge assembly code seamlessly with C code. Link libraries automatically use absolute addressing or are compiled in relative mode, and linked with other software modules to get absolute addressing.

C Language Compilers. C language compilers are available that support the PSoC family of devices. The products allow you to create complete C programs for the PSoC family devices. The optimizing C compilers provide all of the features of C, tailored to the PSoC architecture. They come complete with embedded libraries providing port and bus operations, standard keypad and display support, and extended math functionality.

Debugger

PSoC Designer has a debug environment that provides hardware in-circuit emulation, allowing you to test the program in a physical system while providing an internal view of the PSoC device. Debugger commands allow you to read and program and read and write data memory, and read and write I/O registers. You can read and write CPU registers, set and clear breakpoints, and provide program run, halt, and step control. The debugger also allows you to create a trace buffer of registers and memory locations of interest.

Online Help System

The online help system displays online, context-sensitive help. Designed for procedural and quick reference, each functional subsystem has its own context-sensitive help. This system also provides tutorials and links to FAQs and an Online Support Forum to aid the designer.

In-Circuit Emulator

A low-cost, high-functionality In-Circuit Emulator (ICE) is available for development support. This hardware can program single devices.

The emulator consists of a base unit that connects to the PC using a USB port. The base unit is universal and operates with all PSoC devices. Emulation pods for each device family are available separately. The emulation pod takes the place of the PSoC device in the target board and performs full-speed (24-MHz) operation.

Designing with PSoC Designer

The development process for the PSoC® device differs from that of a traditional fixed function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and by lowering inventory costs. These configurable resources, called PSoC Blocks, have the ability to implement a wide variety of user-selectable functions. The PSoC development process is summarized in four steps:

1. Select [User Modules](#).
2. Configure user modules.
3. Organize and connect.
4. Generate, verify, and debug.

Select User Modules

PSoC Designer provides a library of prebuilt, pretested hardware peripheral components called “user modules.” User modules make selecting and implementing peripheral devices, both analog and digital, simple.

Configure User Modules

Each user module that you select establishes the basic register settings that implement the selected function. They also provide parameters and properties that allow you to tailor their precise configuration to your particular application. For example, a pulse width modulator (PWM) User Module configures one or more digital PSoC blocks, one for each 8 bits of resolution. The user module parameters permit you to establish the pulse width and duty cycle. Configure the parameters and properties to correspond to your chosen application. Enter values directly or by selecting values from drop-down menus. All the user modules are documented in datasheets that may be viewed directly in PSoC Designer or on the Cypress website. These [user module datasheets](#) explain the internal operation of the user module and provide performance specifications. Each datasheet describes the use of each user module parameter, and other information you may need to successfully implement your design.

Organize and Connect

You build signal chains at the chip level by interconnecting user modules to each other and the I/O pins. You perform the selection, configuration, and routing so that you have complete control over all on-chip resources.

Generate, Verify, and Debug

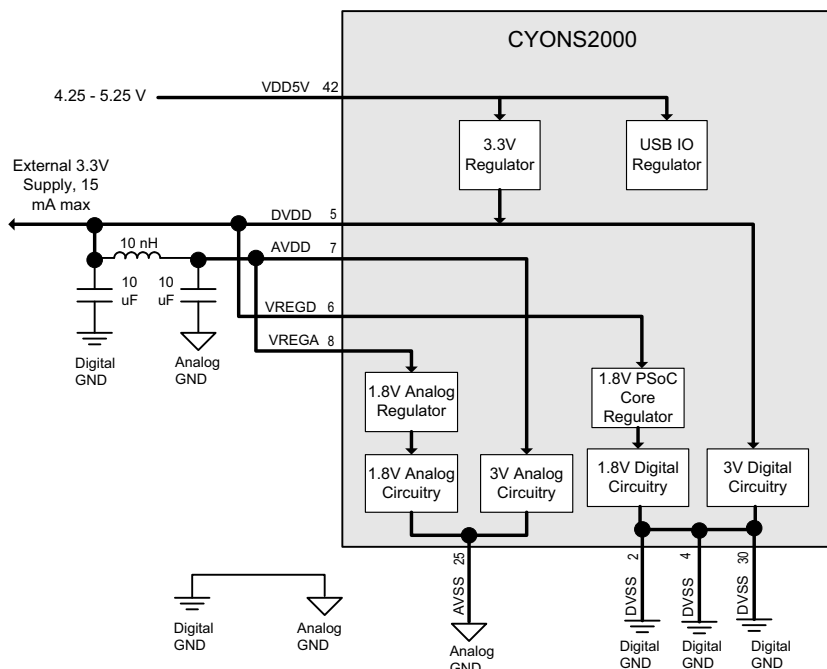
When you are ready to test the hardware configuration or move on to developing code for the project, you perform the “Generate Configuration Files” step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the software for the system. The generated code provides application programming interfaces (APIs) with high-level functions to control and respond to hardware events at run time and interrupt service routines that you can adapt as needed.

A complete code development environment allows you to develop and customize your applications in either C, assembly language, or both.

The last step in the development process takes place inside PSoC Designer’s debugger (access by clicking the Connect icon). PSoC Designer downloads the HEX image to the ICE where it runs at full speed. PSoC Designer debugging capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint and watch-variable features, the debug interface provides a large trace buffer and allows you to define complex breakpoint events that include monitoring address and data bus values, memory locations and external signals.

Power Supply Connections

Figure 4. Power Connections Block Diagram



Overview

The CYONS2000 incorporates a powerful and flexible powering system. It can be powered from one of two sources: a 5-V supply (typically from the USB VBUS line) or an external 3.3-V supply. Additionally, the CYONS2000's internal regulators can supply current to external devices. This section describes the capabilities and usage of the power system. Refer to [Figure 4](#) for a block diagram of the CYONS2000's power system.

Understanding DVDD

DVDD is a unique pin because it serves as either an input or an output. When the device is powered from USB (using the 3.3-V regulator), DVDD acts as an output, providing a 3.3-V voltage that can be used to power AVDD, VREGD, VREGA, and external parts. When the device is powered from an external 3.3-V supply, DVDD acts as an input only.

AVDD, VREGA, and VREGD

As with DVDD, these signals power the internal circuitry of the device. Unlike DVDD, these are always inputs. They should be connected as shown in [Figure 4](#).

Using USB Power

For most USB applications, the device is powered from the USB VBUS signal. In this case, the 5-V VBUS signal should be connected directly to the CYONS2000's VDD5V pin.

Using External Power

The CYONS2000 can also be powered from an external source. In this case, the external 3.3-V source should connect to DVDD, and the VDD5V pin should be left unconnected.

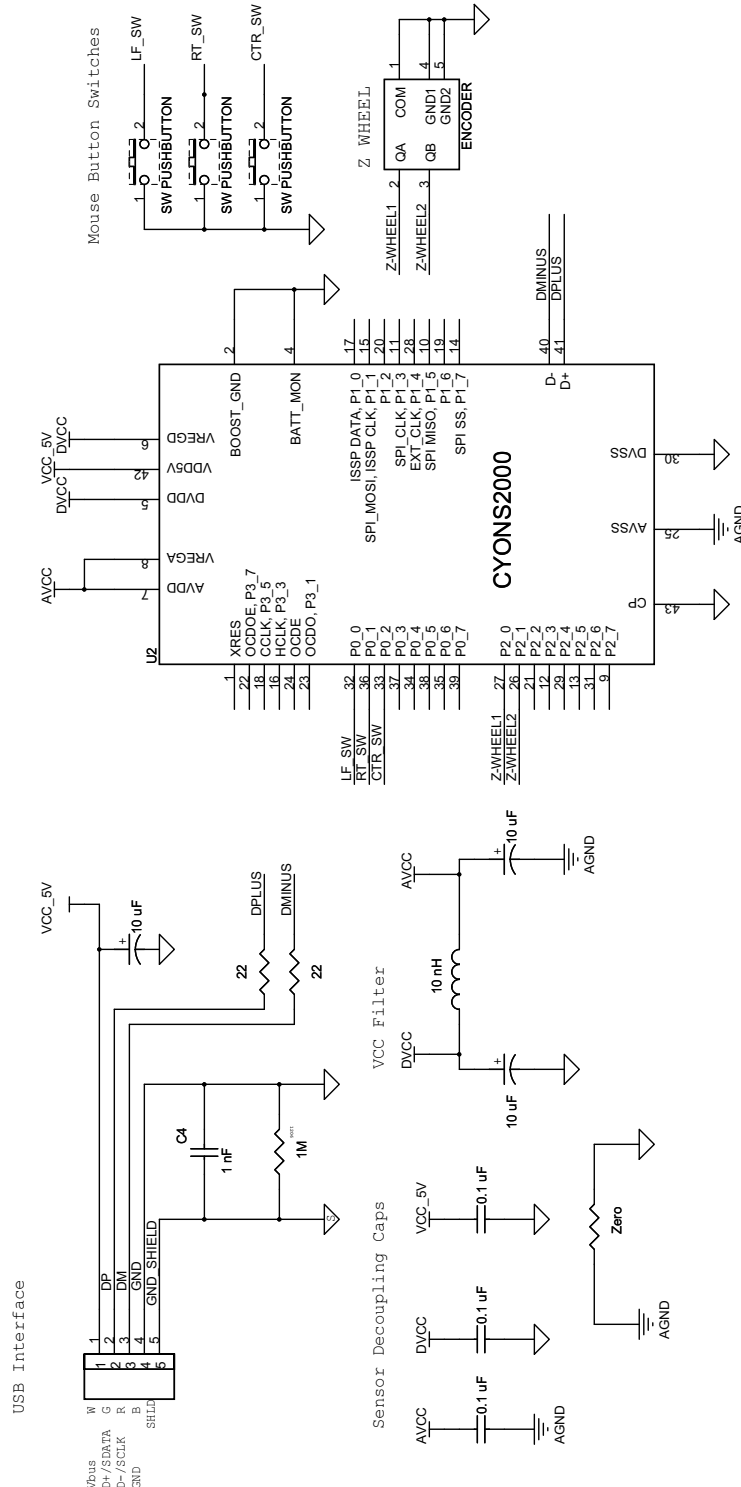
Filtering and Grounding

For all designs, it is important to provide proper grounding, and proper isolation between the analog and digital power supplies. The analog and digital grounds should be isolated, except for a single connection point that is placed as close as possible to the device. On the supply side, an L-C filter should be placed between AVDD and DVDD, as shown in [Figure 4](#).

Wired Mouse Application Example

Figure 5 shows an implementation of a wired mouse. For complete details, refer to the [CY4631 - OvationONS™ II Laser Gaming Mouse Reference Design Kit](#).

Figure 5. Wired Mouse



Electrical Specifications

This section presents the DC and AC electrical specifications of the CYONS2000 device. For the most up-to-date electrical specifications, confirm that you have the most recent datasheet by visiting <http://www.cypress.com>.

Absolute Maximum Ratings

Parameter	Min	Typ	Max	Unit	Conditions
Storage temperature ^[2]	−40	25	65	°C	Case temperature
Operating temperature	−5		55	°C	Case temperature
Lead solder temperature	—	—	260	°C	10 seconds
Supply voltage, DVDD, AVDD, VREGA, and VREGD relative to DVSS	—	—	3.6	V	
Supply voltage, VDD5V relative to DVSS	—	—	5.5	V	
Electrostatic discharge (ESD)	—	—	2.0	kV	All pins, HBM MIL 883 method 3015
I/O Voltage relative to DVSS	−0.5	—	DVDD + 0.5	V	GPIO ports 0, 2, and 3
I/O voltage relative to DVSS	—	—	5.5	V	GPIO port 1
Latch up current	—	—	100	mA	
Maximum current into any GPIO pin	−25	—	+50	mA	

Operating Conditions

Parameter	Min	Typ	Max	Unit	Conditions
Operating temperature	5	—	45	°C	
Power supply voltage VDD5V DVDD, AVDD, VREGD VREGA	4.35 2.70 1.71	—	5.25 3.60 3.60	V	
Power supply rise time	100	—	—	μs	
Supply noise – AVDD (sinusoidal)	—	—	25	mV pp	10 kHz to 50 MHz
Supply noise – V _{DD} , DVDD (sinusoidal)	—	—	100	mV pp	10 kHz to 50 MHz
Distance from PCB to tracking surface	5.80	6	6.20	mm	See Figure 15 on page 26
PCB thickness	1.54	—	1.79	mm	See Figure 15 on page 26

Note

- High storage temperature reduces flash data retention time specified in [Table 7](#) on page 18. Recommended storage temperature is 25 ± 25 °C. Extended duration above 65 °C can degrade reliability.

Power Consumption

Introduction

As described in [Overview](#) on page 11, the CYONS2000 has a highly advanced power system that can be used to develop very low-power applications. This section describes and specifies the power consumption performance of the device.

Enabling Low Power Modes

In some cases, designers may want to develop “always-on” applications, with no power-saving modes and consequently no wakeup latency in performance. In other applications, conserving power is crucial, and power saving modes are a firm requirement. The CYONS2000 enables low-power modes to be enabled or disabled in firmware, either through register writes or through the application programming interface in Cypress's PSoC Designer development software. The remainder of this section applies to applications requiring power saving modes.

Operating Modes

From a power consumption standpoint, consider these three operating modes:

- **Tracking mode:** In this mode, the device is actively tracking on a surface. It is the highest power mode of the device. The current consumption has a slight dependence on speed and surface. The current, however, is independent of resolution.
- **Inactive mode:** In this mode, the device is in its lowest power state. In inactive mode, the device cannot sense motion, but a timer is running. This timer can generate an interrupt that can wake the rest of the device and start tracking motion.
- **Sleep modes:** In sleep modes, the device self-transitions between tracking mode and inactive mode. The typical use of sleep modes is when the device is at rest, but might still be moved. In Sleep modes, the CYONS2000 stays in inactive mode for a fixed time, then wakes up and checks for motion. If motion is detected, the device fully wakes up and begins tracking. If no motion is detected, the device can go back to Sleep mode.

Power Management Through Sleep Mode Control

Power management for the CYONS2000 consists of setting the parameters that define the sleep modes. The device is equipped

with four sets of sleep mode settings, enabling four levels of sleep. By controlling the parameters of these four sleep modes, the designer can tailor the solution to make appropriate tradeoffs between power consumption and wakeup latency.

The transition between sleep modes is under the control of the CYONS2000's digital signal processor (DSP) – no firmware needs to be written to manage the transition between modes.

Each of the four available sleep modes is defined by three parameters. These parameters are defined as registers that can be controlled by firmware, either through direct register writes or by using the NAV User Module in PSoC Designer.

- **Sleep time:** This is the amount of time that the device is in its low power inactive state.
- **Motion threshold:** This is the amount of motion that is required to bring the device out of sleep.
- **Sleep mode time:** This is the amount of time that the device stays in a particular sleep mode before transitioning to the next lowest sleep mode. Longer sleep times save power but have higher wakeup latency.

[Figure 6](#) shows the flowchart for a particular sleep mode, showing how the three parameters affect behavior.

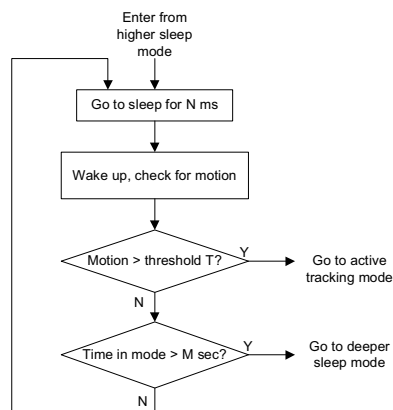
Calculating Power for Sleep Mode

The power consumption in sleep mode can be found by using a duty cycle calculation. The sleep mode current is determined by the tracking mode current, the inactive current, the time required to check for motion (typically 2.9 ms), and the time between check-for-motion events. The expected current consumption is given by the formula

$$I_{\text{SLEEP}} = \frac{I_{\text{TRACK}} \times 2.9 + I_{\text{INACT}} \times T_{\text{SLEEP}}}{2.9 + T_{\text{SLEEP}}}$$

where I_{SLEEP} is the sleep current, I_{TRACK} is the tracking current, I_{INACT} is the inactive current, and T_{SLEEP} is the time (in ms) in the low power state. As an example, if the tracking current is 8.5 mA, the inactive current is 7.5 μA and the sleep time is 100 ms, then the expected sleep current is 0.25 mA.

Figure 6. Sleep Mode Flowchart



Power Specifications

There are two ways to power the CYONS2000 – external powering and USB powering. [Table 4](#) provides the current consumption values for each mode.

With external powering, a 3-V supply is connected to DVDD, AVDD, VREGD, and VREGA, and the internal regulator is turned off. In this case, the current consumption during tracking is $I_{\text{TRACK_EXT}}$, and the consumption during sleep is I_{SLEEP} .

With USB powering, the 5-V USB supply is connected to VDD5V, and DVDD, AVDD, VREGD, and VREGA are driven by the internal regulator. Tracking current is specified by $I_{\text{TRACK_USB}}$. Sleep current must include the current consumption of the regulator itself, and is specified by the sum of I_{SLEEP} and I_{REG5V} . Sleep current is achieved by activating “Navigation Sleep

Modes” in Cypress’s PSoC Designer development environment. Doing so enables the sleep mode progressions described in [Operating Modes](#) on page 14. If sleep modes are not activated, the device current stays at tracking levels, even when the device is not sensing motion.

$I_{\text{SB_EXT}}$ is the current in the lowest-power mode of the device. In this mode, the CPU is halted and operation can only be restarted with an external reset at the XRES pin.

For designs using the CYONS2000, low-power operation is often only needed to support USB Suspend. The reference code for this is available in the [CY4631 - OvationONS™ II Laser Gaming Mouse Reference Design Kit](#).

Table 2. Power Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
$I_{\text{TRACK_EXT}}$	Tracking current into DVDD, AVDD, VREGD, VREGA	3.0 V, 25 °C, 5 in/s, 24-MHz IMO, 6-MHz CPU clock, white surface, nominal tracking height	–	9	12.5	mA
$I_{\text{TRACK_USB}}$	Tracking current into VDD5V	5.25 V, 25 °C, 5 in/s, 24-MHz IMO, 6-MHz CPU clock, white surface, nominal tracking height, DVDD, AVDD, VREGD, and VREGA powered by internal regulator	–	12.5	16	mA
I_{INACT}	Inactive current into DVDD, AVDD, VREGD, VREGA	3.0 V, 25 °C, CPU in sleep state	–	7	14	μA
I_{SLEEP}	Sleep current into DVDD, AVDD, VREGD, VREGA	3.0 V, 25 °C	See Calculating Power for Sleep Mode on page 14 for equation			
I_{REG5V}	5 V-to-3 V regulator current consumption	VDD5V = 5.25 V, regulator active	–	250	–	μA
$I_{\text{SB_EXT}}$	Shutdown current into DVDD, AVDD, VREGD, VREGA, all blocks off	3.0 V, 25 °C, 5-V supply not present	–	4	11	μA
$I_{\text{SB_USB}}$	Shutdown current, all blocks off, into VDD5V	5.25 V, 25 °C, DVDD, AVDD, VREGA, VREGD powered by internal 5-V-to-3-V regulator in standby mode	–	80	–	μA

DC General Purpose I/O Specifications

GPIOs are arranged into four ports. Ports 0, 1, and 2 have eight GPIO pins and Port 3 has four GPIO pins. Port 1 has an optional low drop out (LDO) regulator that adjusts the port's output voltage to 1.8, 2.5, or 3.0 V. Additionally, each GPIO pin can be independently set to one of the four drive modes: strong drive, open drain, pull-up, or high-Z analog.

Rise and fall times are specified for 10% and 90% voltage values.

The following tables list guaranteed maximum and minimum specifications for the voltage range of 2.7 V to 3.6 V at the DVDD pin, and over the temperature range $5^{\circ}\text{C} \leq T_A \leq 45^{\circ}\text{C}$. Typical parameters apply to 3.3 V at 25°C and are for design guidance only.

Table 3. 2.7 V to 3.6 V DC GPIO Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
R _{PU}	Pull-up resistor	Pin configured for pull-up mode.	4.0	5.6	8.0	k Ω
V _{OH1}	High output voltage Port 2 or 3 pins	I _{OH} \leq 10 μA , maximum of 10-mA source current in all I/Os.	DVDD – 0.2	–	–	V
V _{OH2}	High output voltage Port 2 or 3 pins	I _{OH} = 1 mA, maximum of 20-mA source current in all I/Os.	DVDD – 0.9	–	–	V
V _{OH3}	High output voltage Port 0 or 1 pins with LDO regulator disabled for Port 1	I _{OH} $<$ 10 μA , maximum of 10-mA source current in all I/Os.	DVDD – 0.2	–	–	V
V _{OH4}	High output voltage Port 0 or 1 pins with LDO regulator disabled for Port 1	I _{OH} = 5 mA, maximum of 20-mA source current in all I/Os.	DVDD – 0.9	–	–	V
V _{OH5}	High output voltage Port 1 pins with LDO regulator enabled for 3 V Out	I _{OH} $<$ 10 μA , DVDD $>$ 3.1 V, maximum of 4 I/Os all sourcing 5 mA.	2.85	3.00	3.30	V
V _{OH6}	High output voltage Port 1 pins with LDO regulator enabled for 3 V Out	I _{OH} = 5 mA, DVDD $>$ 3.1 V, maximum of 20 mA source current in all I/Os.	2.20	–	–	V
V _{OH7}	High output voltage Port 1 pins with LDO enabled for 2.5 V Out	I _{OH} $<$ 10 μA , DVDD $>$ 2.7 V, maximum of 20 mA source current in all I/Os.	2.35	2.50	2.75	V
V _{OH8}	High output voltage Port 1 pins with LDO enabled for 2.5 V Out	I _{OH} = 2 mA, DVDD $>$ 2.7 V, maximum of 20 mA source current in all I/Os.	1.90	–	–	V
V _{OH9}	High output voltage Port 1 pins with LDO enabled for 1.8 V Out	I _{OH} $<$ 10 μA , DVDD $>$ 2.7 V, maximum of 20 mA source current in all I/Os.	1.60	1.80	2.10	V
V _{OH10}	High output voltage Port 1 pins with LDO enabled for 1.8 V Out	I _{OH} = 1 mA, DVDD $>$ 2.7 V, maximum of 20 mA source current in all I/Os.	1.20	–	–	V
V _{OL}	Low output voltage	I _{OL} = 25 mA, DVDD $>$ 3.3 V, maximum of 60-mA sink current on even port pins (for example, P0[2] and P1[4]) and 60-mA sink current on odd port pins (for example, P0[3] and P1[5]).	–	–	0.75	V
V _{IL}	Input low voltage		–	–	0.80	V
V _{IH}	Input high voltage		2.00	–		V
V _H	Input hysteresis voltage		–	80	–	mV
I _{IL}	Input leakage (absolute value)	Gross tested to 1 μA .	–	0.5	1.0	μA
C _{PIN}	Pin capacitance	Temp = 25°C .	0.5	1.7	8.0	pF

DC Analog Mux Bus Specifications

The analog mux bus can connect signals from GPIOs to and from internal analog blocks and other GPIOs. [Table 4](#) lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 4. DC Analog Mux Bus Specifications

Parameter	Description	Conditions	Min	Typ	Max	Unit
R _{SW}	Switch resistance to common analog bus	Pin voltage < 1.8 V	–	–	800	Ω
R _{GND}	Resistance of initialization switch to DVSS	Pin voltage < 1.8 V	–	–	800	Ω

DC Low Power Comparator Specifications

The device includes two general-purpose comparators, using internal or external signals from the analog mux bus. [Table 5](#) lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 5. DC Comparator Specifications

Parameter	Description	Conditions	Min	Typ	Max	Unit
V _{LPC}	Low power comparator (LPC) common mode	Maximum voltage limited to DVDD.	0.0	–	1.8	V
I _{LPC}	LPC supply current		–	10	40	μA
V _{OSLPC}	LPC voltage offset		–	2.5	30	mV

DC POR and LVD Specifications

The device features two mechanisms for dealing with low power supply voltages. Both power-on reset (POR) and LVD events occur when DVDD falls below a threshold. A POR completely resets the device. An LVD generates an interrupt to the MCU, allowing the application developer to better manage power supply drops.

The POR threshold is defined by bits 7 (HPOR) and 5:4 (PORLEV) and of the VLT_CR register at address E3h in register bank 1. The LVD threshold is defined by bits 2:0 (VM) of the same register. Refer to the [technical reference manual](#) for more details.

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 6. DC POR and LVD Specifications

Parameter	Description	Conditions	Min	Typ	Max	Unit
V _{POR0}	DVDD Value for POR trip PORLEV[1:0] = 00b, HPOR = 0	DVDD must be greater than or equal to 1.71 V during startup, reset from the XRES pin, or reset from watchdog.	1.61	1.66	1.71	V
V _{POR1}	PORLEV[1:0] = 00b, HPOR = 1		–	2.36	2.40	V
V _{POR2}	PORLEV[1:0] = 01b, HPOR = 1		–	2.60	2.65	V
V _{POR3}	PORLEV[1:0] = 10b, HPOR = 1		–	2.82	2.95	V
V _{LVD0}	DVDD Value for LVD trip VM[2:0] = 000b		2.40 ^[3]	2.45	2.51	V
V _{LVD1}	VM[2:0] = 001b		2.64 ^[4]	2.71	2.78	V
V _{LVD2}	VM[2:0] = 010b		2.85 ^[5]	2.92	2.99	V
V _{LVD3}	VM[2:0] = 011b		2.95	3.02	3.09	V
V _{LVD4}	VM[2:0] = 100b		3.06	3.13	3.20	V
V _{LVD5}	VM[2:0] = 101b		1.84	1.90	1.96	V
V _{LVD6}	VM[2:0] = 110b		1.75 ^[6]	1.80	1.84	V

Notes

3. Always greater than 50 mV above V_{POR1} voltage for falling supply.
4. Always greater than 50 mV above V_{POR2} voltage for falling supply.
5. Always greater than 50 mV above V_{POR3} voltage for falling supply.
6. Always greater than 50 mV above V_{POR0} voltage for falling supply.

DC Programming Specifications

Table 7 lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

The CYONS2000 must be properly powered for flash programming, with DVDD, AVDD, VREGD, and VREGA all held within the specified range. A suitable option for in-circuit programming USB designs is to apply 5 V to the VDD5V pin and use the internal regulator to drive DVDD, AVDD, VREGD, and VREGA. This enables direct connection to Cypress's CY3210-Miniprogram. For in-circuit programming of externally powered designs, the designer must include provisions for supplying DVDD, AVDD, VREGD, and VREGA externally.

Table 7. DC Programming Specifications

Parameter	Description	Conditions	Min	Typ	Max	Unit
V _{IW}	Supply voltage for flash write operations	V _{IW} applied to DVDD, AVDD, VREGD, and VREGA	2.7	–	3.6	V
I _{DDP}	Supply current during programming or verify		–	5	25	mA
V _{ILP}	Input low voltage during programming or verify	See DC General Purpose I/O Specifications on page 16.	–	–	V _{IL}	V
V _{IHP}	Input high voltage during programming or verify	See DC General Purpose I/O Specifications on page 16.	V _{IH}	–	–	V
I _{ILP}	Input current when applying V _{ILP} to ISSP CLK and ISSP DATA pins during programming or verify	Driving internal pull-down resistor.	–	–	0.2	mA
I _{IHP}	Input current when applying V _{IHP} to ISSP CLK and ISSP DATA pins during programming or verify	Driving internal pull-down resistor.	–	–	1.5	mA
V _{OLP}	Output low voltage during programming or verify		–	–	DVSS + 0.75	V
V _{OHP}	Output high voltage during programming or verify	DC General Purpose I/O Specifications on page 16. For DVDD > 3 V use the value with I _{OH} = 5 mA.	V _{OH}	–	DVDD	V
Flash _{ENPB}	Flash write endurance	Erase/write cycles by block.	50,000	–	–	Cycles
Flash _{DR}	Flash data retention	Following maximum flash write cycles at ambient temp of 45 °C	5	10	–	Years

DC Characteristics - USB Interface

The device includes an integrated full-speed USB block. Table 8 lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 8. DC USB Characteristics

Symbol	Description	Conditions	Min	Typ	Max	Units
R _{usbi}	USB D+ pull-up resistance	With idle bus	0.900	–	1.575	kΩ
R _{usba}	USB D+ pull-up resistance	While receiving traffic	1.425	–	3.090	kΩ
V _{ohusb}	Static output high		2.8	–	3.6	V
V _{olusb}	Static output low		–	–	0.3	V
V _{di}	Differential input sensitivity		0.2	–	–	V
V _{cm}	Differential input common mode range		0.8	–	2.5	V
V _{se}	Single-ended receiver threshold		0.8	–	2.0	V
C _{in}	Transceiver capacitance		–	–	50	pF
I _{io}	High-Z state data line leakage	On D+ or D- line	–10	–	+10	uA
R _{ps2}	PS/2 pull-up resistance		3	5	7	kΩ
R _{ext}	External USB series resistor	In series with each USB pin	21.78	22	22.22	Ω

AC Chip Level Specifications

The device has two internal oscillators. The IMO controls the clock speeds for the CPU. A programmable frequency divider allows the CPU to run at lower speeds than the IMO. The ILO is a typically active in sleep modes, clocking sleep, and watchdog timers. Other internal timers can be clocked by either the CPU clock or the ILO.

Table 9 lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 9. AC Chip Level Specifications

Parameter	Description	Min	Typ	Max	Unit
F _{IMO24}	IMO frequency for 24-MHz setting	22.8	24	25.2	MHz
F _{IMO12}	IMO frequency for 12-MHz setting	11.4	12	12.6	MHz
F _{IMO6}	IMO frequency for 6-MHz setting	5.7	6.0	6.3	MHz
DC _{IMO}	IMO output duty cycle at 6 and 12-MHz setting ^[7]	40	50	60	%
F _{CPU}	CPU frequency ^[8]	F _{IMO} / 256	–	F _{IMO}	MHz
F _{32K1}	ILO frequency ^[9]	19	32	50	kHz
T _{RAMP}	Supply ramp time	20	–	–	μs
TXRST	External reset pulse width at power-up	1	–	–	ms
TXRST2	External reset pulse width after power-up	10	–	–	μs
TMOT	Motion delay from reset to valid tracking data ^[10]	–	–	30	ms

AC General Purpose I/O/I/O Specifications

GPIOs are arranged into four ports. Ports 0, 1, and 2 have eight GPIO pins and Port 3 has four GPIO pins. Port 1 has an optional LDO regulator that adjusts the port's output voltage to 1.8, 2.5, or 3.0 V. Additionally, each GPIO pin can be independently set to one of four drive modes: strong drive, open drain, pull-up, or high-Z analog.

Rise and fall times are specified for 10% and 90% voltage values.

Specifications are for the entire operating temperature range.

Table 10. AC GPIO Specs

Parameter	Description	Conditions	Min	Typ	Max	Units
F _{GPIO}	GPIO operating frequency	Strong drive	0	–	12	MHz
T _{RISE_01}	Rise time, ports 0 -1	Strong drive, C _{LOAD} = 50 pF, DVDD = 3.0 - 3.6	–	–	50	ns
T _{RISE_01_L}	Rise time, ports 0 -1, low supply	Strong drive, C _{LOAD} = 50 pF, DVDD = 2.7 - 3.0	–	–	70	ns
T _{RISE_LDO_3}	Rise time, port 1, 3 V LDO enabled	Strong drive, C _{LOAD} = 50 pF, DVDD > 3.1 V	–	–	50	ns
T _{RISE_LDO_2.5}	Rise time, port 1, 2.5 LDO enabled	Strong drive, C _{LOAD} = 50 pF, DVDD > 2.7 V	–	–	70	ns
T _{RISE_LDO_1.8}	Rise time, port 1, 1.8 LDO enabled	Strong drive, C _{LOAD} = 50 pF, DVDD > 2.7 V	–	–	100	ns
T _{RISE_23}	Rise time, ports 2 - 3	Strong drive, C _{LOAD} = 50 pF, DVDD = 2.7 - 3.6	–	–	80	ns
T _{FALL}	Fall time, all ports	Strong drive, C _{LOAD} = 50 pF, DVDD = 3.0 - 3.6	–	–	50	ns
T _{FALL_L}	Fall time, all ports, low supply	Strong drive, C _{LOAD} = 50 pF, DVDD = 2.7 - 3.0	–	–	70	ns
T _{FALL_LDO_3}	Fall time, port 1, 3 V LDO enabled	Strong drive, C _{LOAD} = 50 pF, DVDD > 3.1 V	–	–	50	ns
T _{FALL_LDO_2.5}	Fall time, port 1, 2.5 LDO enabled	Strong drive, C _{LOAD} = 50 pF, DVDD > 2.7 V	–	–	70	ns
T _{FALL_LDO_1.8}	Fall time, port 1, 1.8 LDO enabled	Strong drive, C _{LOAD} = 50 pF, DVDD > 2.7 V	–	–	80	ns

Notes

- IMO can be output from chip by routing to GPIO. Maximum GPIO output frequency is 12 MHz, so duty cycle at 24 MHz is not defined. See Technical Reference Manual at www.cypress.com or in Cypress's PSoC Designer software for details on routing IMO to GPIO pin.
- Available frequency divisors are 1, 2, 4, 8, 16, 32, 128, and 256.
- 32 kHz oscillator can be locked to external crystal. See technical reference manual available at www.cypress.com or in Cypress' PSoC Designer software.
- Value provided represents maximum startup time for typical application. Applications requiring additional startup code, processing, or delay may increase TMOT.

AC External Clock Specifications

The IMO can be replaced with an external clock at the EXT CLK / P[1]4 pin. Refer to the [technical reference manual](#) for more details.

[Table 11](#) lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 11. AC External Clock Specifications

Parameter	Description	Min	Typ	Max	Unit
F _{OSCEXT}	Frequency	0.750	–	25.2	MHz
–	High period	20.6	–	5300	ns
–	Low period	20.6	–	–	ns
–	Required time to run from IMO before switching to external clock	150	–	–	μs

AC Analog Mux Bus Specifications

[Table 12](#) lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 12. AC Analog Mux Bus Specifications

Parameter	Description	Conditions	Min	Typ	Max	Unit
F _{SW}	Switch rate	Pin voltage < 1.8 V	–	–	6.3	MHz

AC Programming Specifications

The analog mux bus can connect signals from GPIOs to and from internal analog blocks and other GPIOs. [Table 13](#) lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 13. AC Programming Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
T _{RSCLK}	Rise time of ISSP CLK		1	–	20	ns
T _{FSCLK}	Fall time of ISSP CLK		1	–	20	ns
T _{SSCLK}	Data setup time to falling edge of ISSP CLK		40	–	–	ns
T _{HSCLK}	Data hold time from falling edge of ISSP CLK		40	–	–	ns
F _{SCLK}	Frequency of ISSP CLK		0	–	8	MHz
T _{ERASEB}	Flash erase time (Block)		–	–	18	ms
T _{WRITE}	Flash block write time		–	–	25	ms
T _{DSCLK2}	Data out delay from falling edge of ISSP CLK	3.0 ≤ DVDD ≤ 3.6	–	–	85	ns

AC SPI Specifications

Table 14 lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 14. AC SPI Master Specifications

Parameter	Description	Min	Typ	Max	Unit
f_{SCLK}	SPI CLK frequency ^[11]	–	–	$F_{IMO}/2$	MHz
t_{SETUP}	SPI MISO to SPI CLK setup time	60	–	–	ns
t_{HOLD}	SPI CLK to SPI MISO hold time	40	–	–	ns
t_{OUT_SU}	SPI MOSI to SPI CLK setup time	40	–	–	ns
t_{OUT_H}	SPI CLK to SPI MOSI hold time	40	–	–	ns

Table 15. AC SPI Slave Specifications

Parameter	Description	Min	Typ	Max	Unit
f_{SCLK}	SPI CLK frequency ^[11]	–	–	12	MHz
t_{LOW}	Minimum SPI CLK low width ^[12]	41.67	–	–	ns
t_{HIGH}	Minimum SPI CLK high width ^[12]	41.67	–	–	ns
t_{SETUP}	SPI MOSI to SPI CLK setup time	25	–	–	ns
t_{HOLD}	SPI CLK to SPI MOSI hold time	25	–	–	ns
t_{OUT_H}	SPI CLK to SPI MISO hold time	35	–	–	ns
t_{SS_MISO}	SPI SS to SPI MISO valid	–	–	100	ns
t_{SCLK_MISO}	SPI CLK to SPI MISO valid	–	–	140	ns
t_{SS_HIGH}	Minimum SPI SS high width	–	–	35	ns
t_{SS_CLK}	Time from SPI SS low to first SPI CLK	–	–	20	ns
t_{CLK_SS}	Time from last SPI CLK to SPI SS high	–	–	25	ns

Notes

11. Clock frequency is half of clock input to SPI block.
 12. Value corresponds to 50% duty cycle at 12 MHz.

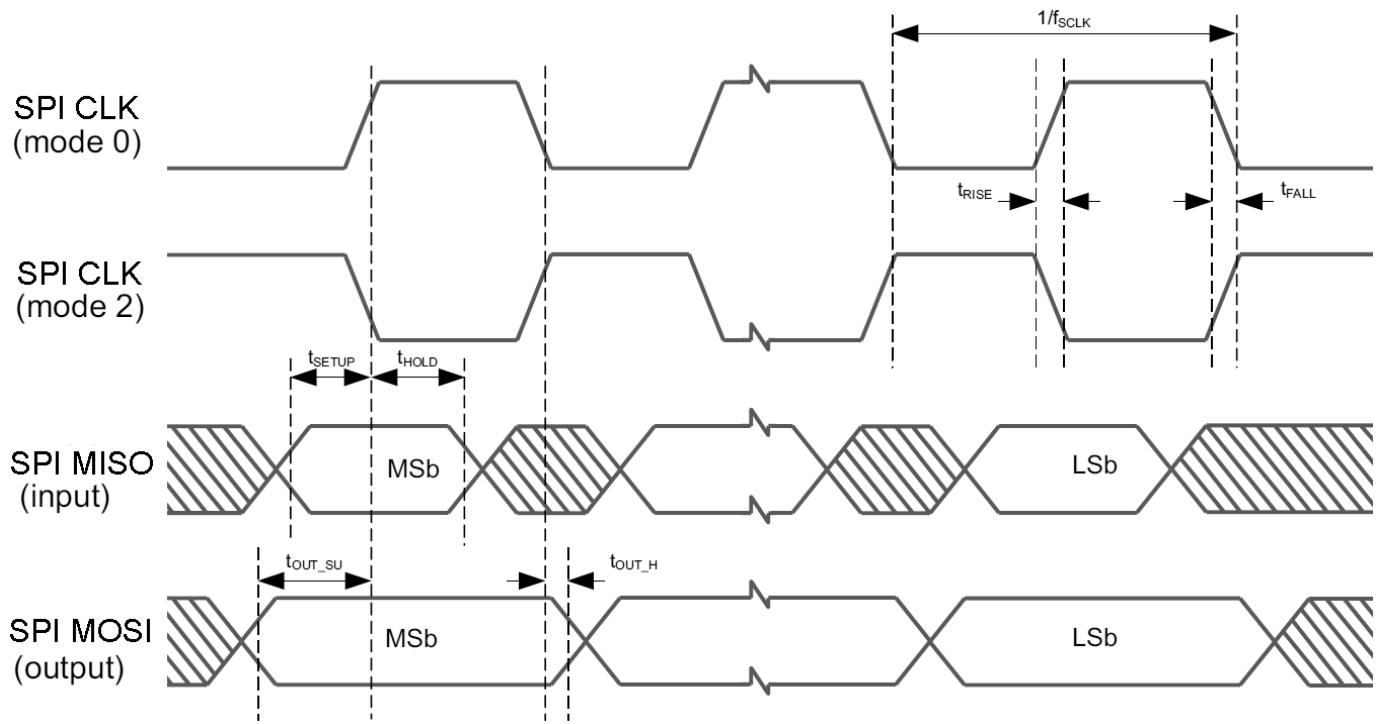
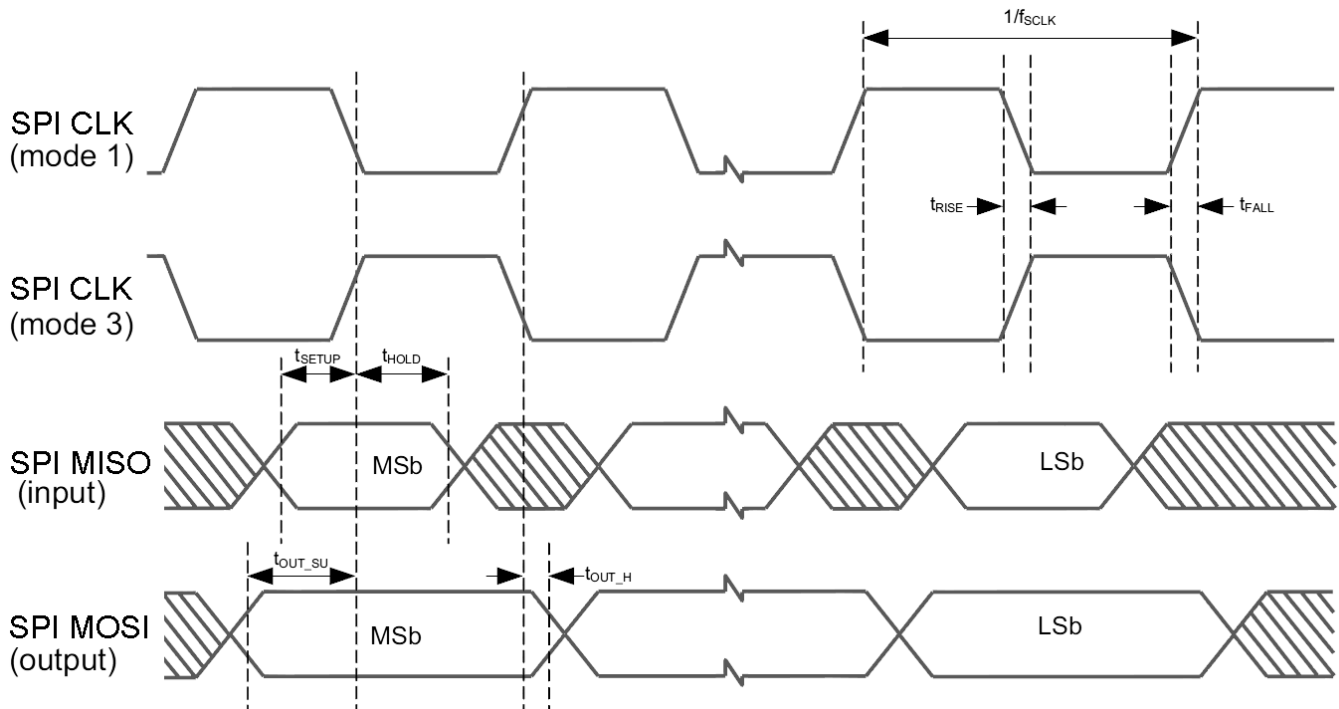
Figure 7. SPI Master Timing Diagram, Modes 0 and 2

Figure 8. SPI Master Timing Diagram, Modes 1 and 3


Figure 9. SPI Slave Timing Diagram, Modes 0 and 2

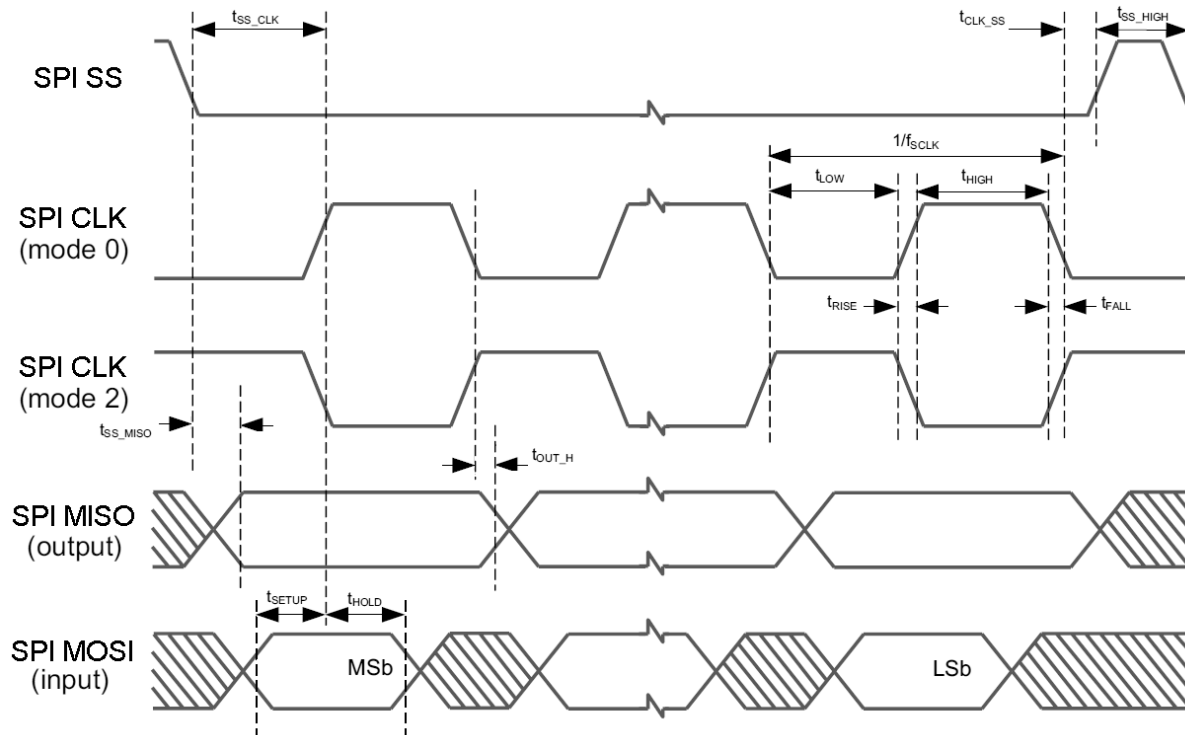
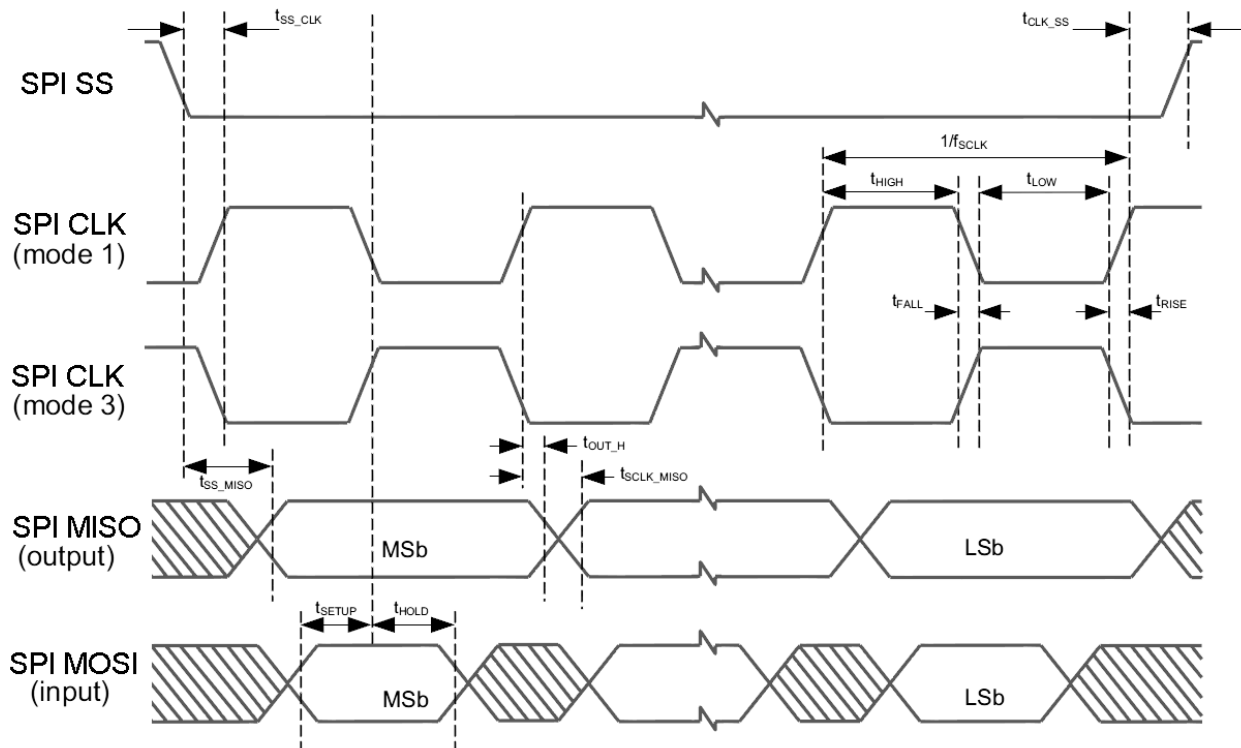


Figure 10. SPI Slave Timing Diagram, Modes 1 and 3



AC Comparator Specifications

The device includes two general-purpose comparators, using internal or external signals from the analog mux bus. Table 16 lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 16. AC Low Power Comparator Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
T_{LPC}	Comparator response time, 50 mV overdrive	50 mV overdrive does not include offset voltage	–	–	100	ns

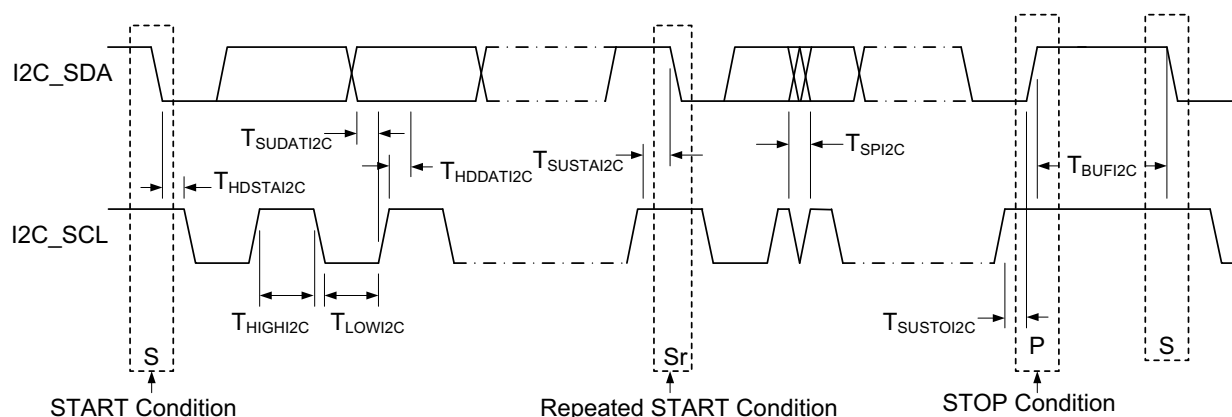
AC I²C Specifications

The following table lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 17. AC Characteristics of the I²C SDA and SCL Pins

Symbol	Description	Standard Mode		Fast Mode		Units
		Min	Max	Min	Max	
F_{SCL2C}	I2C_SCL clock frequency	0	100	0	400	kHz
$T_{HDSTA2C}$	Hold time for START and Repeated START condition	4.0	–	0.6	–	μ s
T_{LOW2C}	LOW period of the I2C_SCL clock	4.7	–	1.3	–	μ s
T_{HIGH2C}	HIGH period of I2C_SCL clock	4.0	–	0.6	–	μ s
$T_{SUSTA2C}$	Setup time for a START and Repeated START condition	4.7	–	0.6	–	μ s
$T_{HDDAT2C}$	Data hold time	0	–	0	–	μ s
$T_{SUDAT2C}$	Data setup time	250	–	100 ^[13]	–	ns
$T_{SUSTOI2C}$	Setup time for STOP condition	4.0	–	0.6	–	μ s
T_{BUFI2C}	Bus free time between a STOP and START condition	4.7	–	1.3	–	μ s
T_{SPI2C}	Pulse width of spikes that are suppressed by the input filter	–	–	0	50	ns

Figure 11. Timing for Fast/Standard Mode on the I²C Bus



Note

13. A Fast-Mode I2C-bus device can be used in a Standard Mode I2C-bus system, but the requirement $t_{SUDAT2C} \geq 250$ ns must then be met. This automatically is the case if the device does not stretch the LOW period of the SCL signal. If such device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line $t_{rmax} + t_{SUDAT2C} = 1000 + 250 = 1250$ ns (according to the Standard-Mode I2C-bus specification) before the SCL line is released.

AC USB Specifications

The device includes an integrated full-speed USB block. [Table 18](#) lists guaranteed maximum and minimum specifications for the entire voltage and temperature ranges.

Table 18. AC Characteristics – USB Data Timing Specifications

Symbol	Description	Conditions	Min	Typ	Max	Units
Tdrate	Full speed data rate	Average bit rate	12–0.25%	12	12 + 0.25	MHz
Tdjr1	Receiver data jitter tolerance	To next transition	–18.5	–	18.5	ns
Tdjr2	Receiver data jitter tolerance	To pair transition	–9	–	9	ns
Tudj1	Driver differential jitter	To next transition	–3.5	–	3.5	ns
Tudj2	Driver differential jitter	To pair transition	–4.0	–	4.0	ns
Tfdeop	Source jitter for differential transition	To SE0 transition	–2	–	5	ns
Tfeopt	Source SE0 interval of EOP		160	–	175	ns
Tfeopr	Receiver SE0 interval of EOP		82	–		ns
Tfst	Width of SE0 interval during differential transition		–	–	14	ns

Table 19. AC Characteristics – USB Driver

Symbol	Description	Conditions	Min	Typ	Max	Units
Tr	Transition rise time	50 pF	4	–	20	ns
Tf	Transition fall time	50 pF	4	–	20	ns
TR	Rise/fall time matching	0.8 V to 2.5 V	90	–	111	%
Vcrs	Output signal crossover voltage		1.3	–	2.0	V

PCB Land Pads and Keepout Zones

Figure 12 and Figure 13 show the recommended land pad architecture and keepout zones. The pads on the 42-pin device are a subset of the JEDEC MO-220 52-pin QFN standard. For detailed layout instructions, see the application note AN48995, *Mechanical Design Considerations for the OvationONS™ II Laser Navigation System-on-Chip*.

Figure 12. Land Pad Architecture and Spacing

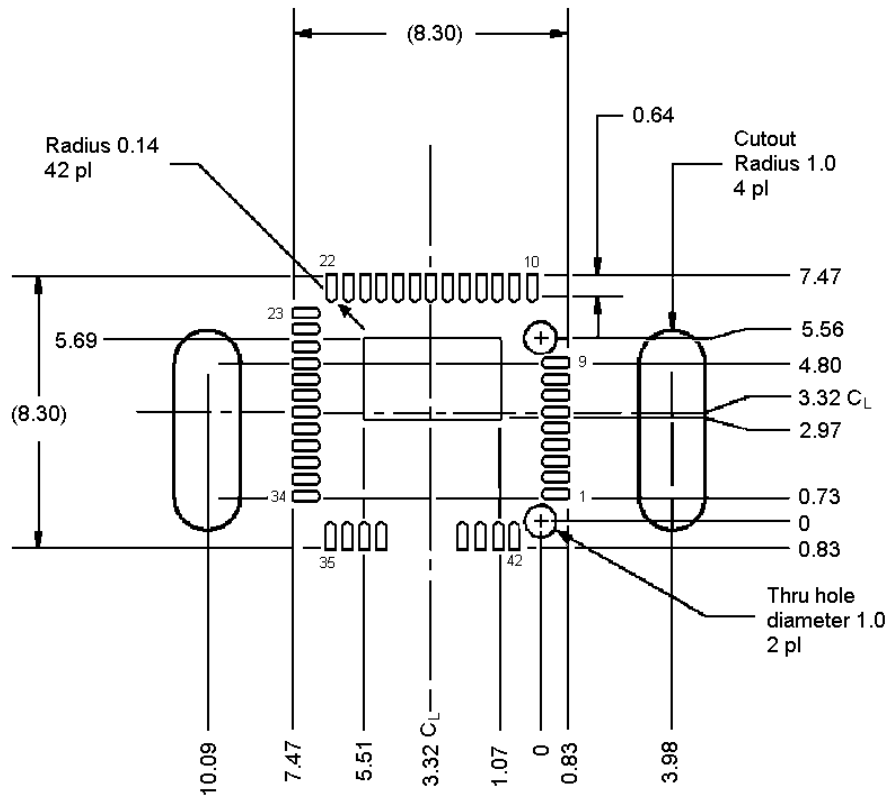
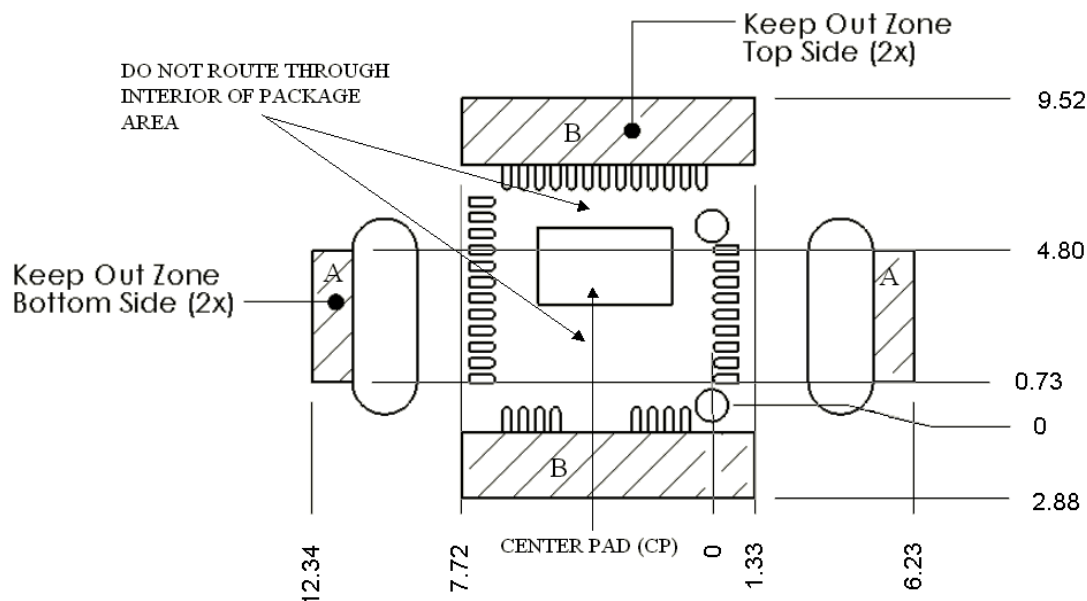


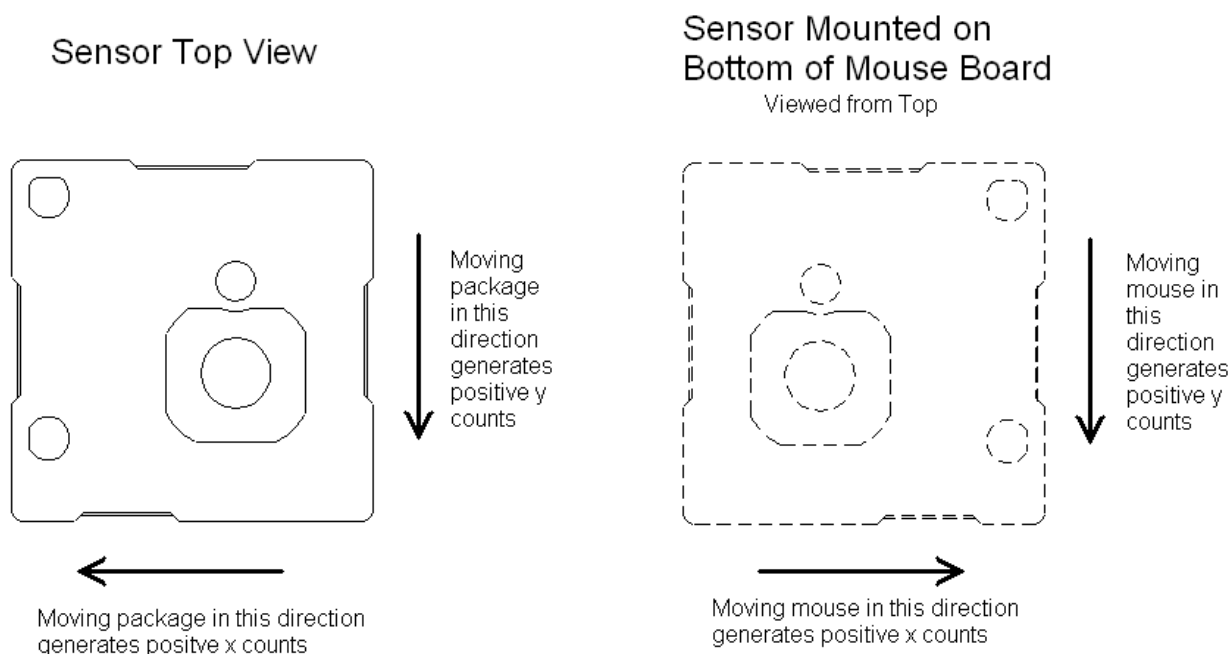
Figure 13. PCB Keep Out Zones



Orientation of Axes

Figure 14 describes the relationship between the package and the x/y axes when using the API provided by Cypress's PSoC Designer software. Note that there is a 90-degree rotation between the orientation below and the orientation described in the register section of the [technical reference manual](#). If PSoC Designer is not used, the application firmware should read and invert the Y count register for X data, and read the X count register for Y data.

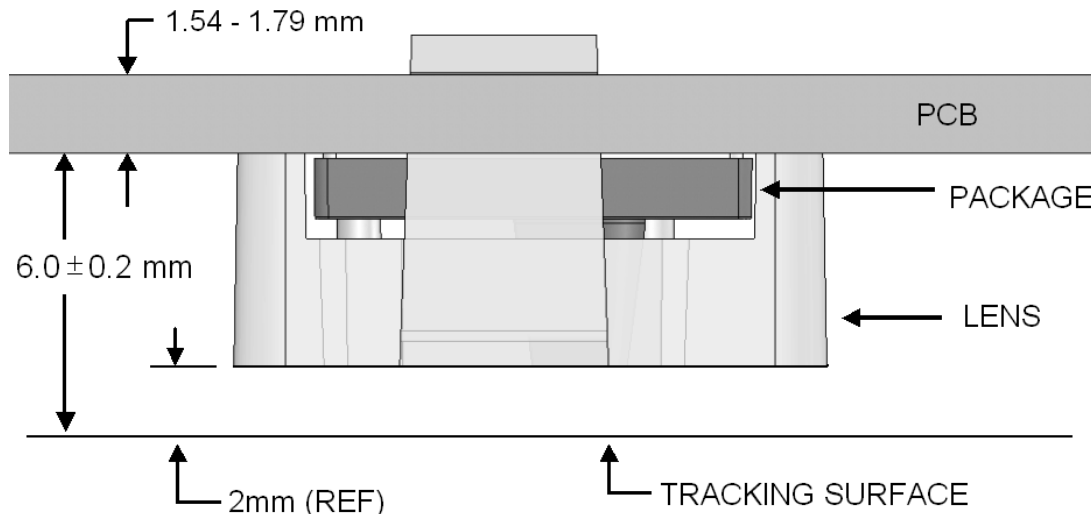
Figure 14. Sensor Orientation when using Cypress PSoC Designer Software



PCB Mounting Height and Thickness

Figure 15 shows the recommended thickness and mounting height of the PCB above the tracking surface.

Figure 15. PCB Height and Thickness



Thermal Impedances

Package	Typical θ_{JA} ^[14]
42 PQFN ^[15]	24 °C/W

Solder Reflow Peak Temperature

Following is the minimum solder reflow peak temperature to achieve good solderability.

Package	Minimum Peak Temperature ^[16]	Maximum Peak Temperature
42 PQFN	240 °C	260 °C

Notes

14. $T_J = T_A + \text{Power} \times \theta_{JA}$.

15. To achieve the thermal impedance specified for the QFN package, the center thermal pad must be soldered to the PCB ground plane.

16. Higher temperatures may be required based on the solder melting point. Typical temperatures for solder are $220 \pm 5^\circ\text{C}$ with Sn-Pb or $245 \pm 5^\circ\text{C}$ with Sn-Ag-Cu paste. Refer to the solder manufacturer specifications. For a recommended soldering profile, refer to Application Note 49035, *Manufacturing Considerations for the Ovation-ONS™ Laser Navigation System-on-Chip*.

Laser Safety Considerations

The CYONS2000 laser navigation SoC and the CYONSLENS2000 lens are designed and tested to enable manufacturers to achieve eye-safety certification with minimal effort. This section provides guidelines for complying with the Class 1 emission requirements of IEC/EN 60825-1.

When installed and operated in accordance with all requirements in this datasheet, the kit consisting of the CYONS2000 laser navigation SoC and CYONSLENS2000 satisfies CDRH 21 CFR 1040 per Laser Notice 50 and IEC/EN 60825-1 Class 1.

Laser Output Power

The CYONS2000 sensor package contains an integrated VCSEL and drive circuitry. Before shipping, Cypress adjusts the laser output power to eye-safe levels, taking into account specified variations in supply voltage, temperature, lens transmission, and VCSEL polarization, and factors such as VCSEL aging and test equipment accuracy. The output remains within eye-safe limits under reasonably foreseeable single-faults, as required by the IEC standard.

From the perspective of a manufacturer, laser emission remains within the Class 1 limit, as defined in IEC 60825-1, Edition 2, 2007, provided the following requirements are met.

- The supply voltage applied to pins DVDD and AVDD of the SoC must be in the range of 2.7 to 3.6 V.
- The operating temperature must be between 5 and 45 °C.
- The laser output power must not be increased by any means, including but not limited to firmware, hardware, or mechanical modifications to the sensor or lens.
- The mechanical housing must be designed such that the CYONSLENS2000 cannot be removed by the user.
- The device firmware must initialize the VCSEL driver as described in the “VCSEL Driver” chapter of the [OvationONS II technical reference manual](#), or by using the NAV or LaserNAV User Modules in Cypress’s PSoC Designer software.

The manufacturer must ensure that these conditions are always met and demonstrate end-product compliance to the appropriate regulatory standards.

Laser Output Power Test Procedure

To verify the laser output level, follow the steps shown in the “VCSEL Power Calibration and Verification” section of the [technical reference manual](#).

Registration Assistance

The mouse or end-product supplier is responsible for certifying the end-use product with respect to the drive voltage, manuals and labels, and operating temperature specifications. Additionally, for products sold in the US, a CDRH report must be filed for each model produced, and test and inspection of the product’s characteristics as they relate to laser safety and the CDRH requirements must be performed.

When filing a report with the CDRH, the supplier can refer to the product report filed by Cypress for the CYONS2xxx family of products. The Cypress report is based on the previously-noted limits for voltage and temperature, and describes how the sensor design includes consideration of drive circuit failures, laser output variation with temperature, drive circuit variation with temperature and voltage, polarization sensitivity of molded optics, and measurement uncertainties.

Cypress can provide assistance to customers who want to obtain registration. Supporting documentation, including a verification test procedure to demonstrate end-product compliance with IEC and CDRH requirements is available.

Development Tool Selection

This section presents the development tools available for all current PSoC device families including the CYONS2000.

Software

PSoC Designer

At the core of the PSoC development software suite is PSoC Designer, used to generate PSoC firmware applications. PSoC Designer is available free of charge at <http://www.cypress.com/psocdesigner> and includes a free C compiler with version Service Pack 4.5 or later.

PSoC Programmer

Flexible enough to be used on the bench in development, yet suitable for factory programming, PSoC Programmer works either as a standalone programming application or operates directly from PSoC Designer. PSoC Programmer software is compatible with both PSoC ICE-Cube In-Circuit Emulator and PSoC MiniProg. PSoC programmer is available free of charge at <http://www.cypress.com/psocprogrammer>.

Mouse Design Kits

Two kits featuring the OvationONS II family of products are available. The reference design kit provides a complete hardware, firmware, and software solution, ready for production. The demonstration kit provides tested hardware and firmware that demonstrate the capabilities of the OvationONS II device.

- CY4631 Wired Mouse reference design kit
- Wireless Mouse demonstration kit

Development Kits

You can purchase the development kits from the Cypress Online Store.

CY3215-DK Basic Development Kit

The [CY3215-DK](#) kit enables prototyping and development with PSoC Designer. This kit supports in-circuit emulation and the software interface enables users to run, halt, and single step the processor and view the content of specific memory locations. Advanced emulation features are also supported through PSoC Designer. The kit includes:

- PSoC Designer software CD
- ICE-Cube In-Circuit Emulator
- ICE Flex-Pod for the CY8C29x66 family
- Cat-5 adapter
- Mini-Eval programming board
- 110 ~ 240 V power supply, Euro-Plug adapter

- iMAGEcraft C compiler (registration required)
- ISSP cable
- USB 2.0 cable and Blue Cat-5 cable
- Two CY8C29466-24PXI 28-PDIP chip samples

Evaluation Tools

You can purchase the evaluation tools from the Cypress Online Store.

CY3210-MiniProg1

The [CY3210-MiniProg1](#) kit enables a user to program PSoC devices using the MiniProg1 programming unit. The MiniProg is a small, compact prototyping programmer that connects to the PC through a provided USB 2.0 cable. The kit includes:

- MiniProg programming unit
- MiniEval socket programming and evaluation board
- 28-pin CY8C29466-24PXI PDIP PSoC device sample
- 28-pin CY8C27443-24PXI PDIP PSoC device sample
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

CY3210-PSoCEval1

The [CY3210-PSoCEval1](#) kit features an evaluation board and the MiniProg1 programming unit. The evaluation board includes an LCD module, potentiometer, LEDs, and plenty of bread-boarding space to meet all your evaluation needs. The kit includes:

- Evaluation board with LCD module
- MiniProg programming unit
- 28-pin CY8C29466-24PXI PDIP PSoC device sample (2)
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

CY3214-PSoCEvalUSB

The [CY3214-PSoCEvalUSB evaluation kit](#) features a development board for the CY8C24794-24LFXI PSoC device. Special features of the board include both USB and capacitive sensing development and debugging support. This evaluation board also includes a LCD module, potentiometer, LEDs, an enunciator and plenty of breadboarding space to meet all of your evaluation needs. The kit includes:

- PSoCEvalUSB board
- LCD module
- MiniProg programming unit
- Mini USB cable
- PSoC Designer and example projects CD
- Getting Started guide
- Wire pack

Device Programmers

You can purchase the device programmers from the Cypress Online Store.

CY3216 Modular Programmer

The [CY3216 Modular Programmer kit](#) features a modular programmer and the MiniProg1 programming unit. The modular programmer includes three programming module cards and supports multiple Cypress products. The kit includes:

- Modular programmer base
- Three programming module cards
- MiniProg programming unit
- PSoC Designer software CD
- Getting Started guide
- USB 2.0 cable

CY3207ISSP In-System Serial Programmer (ISSP)

The [CY3207ISSP](#) is a production programmer. It includes protection circuitry and an industrial case that is more robust than the MiniProg in a production-programming environment.

Note CY3207ISSP needs special software and is not compatible with PSoC Programmer.

The kit includes:

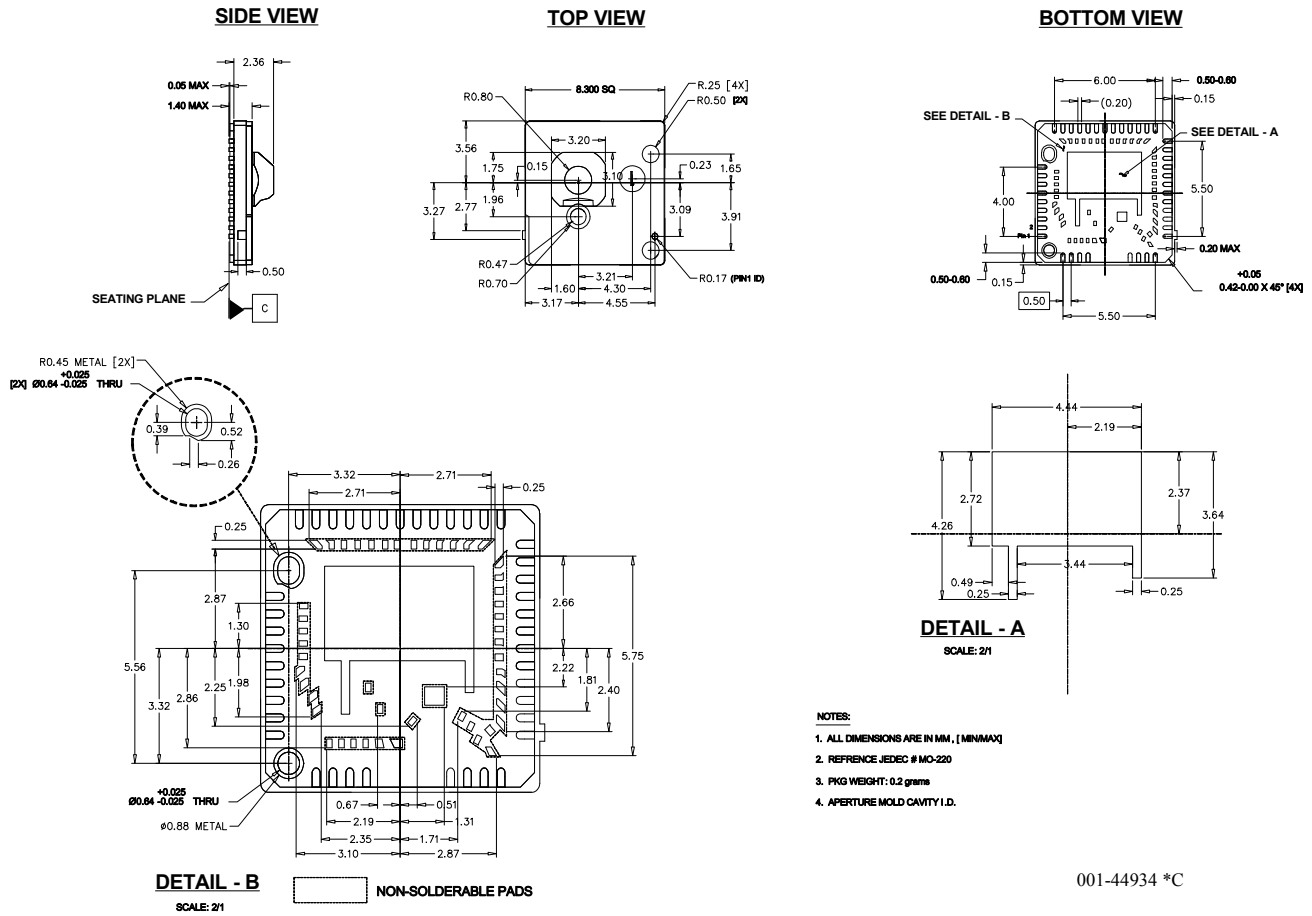
- CY3207 programmer unit
- PSoC ISSP software CD
- 110 ~ 240 V power supply, Euro-Plug adapter
- USB 2.0 cable

Third Party Tools

Several tools have been specially designed by third-party vendors to accompany PSoC devices during development and production. Specific details for each of these tools are found at <http://www.cypress.com>.

Package Diagrams

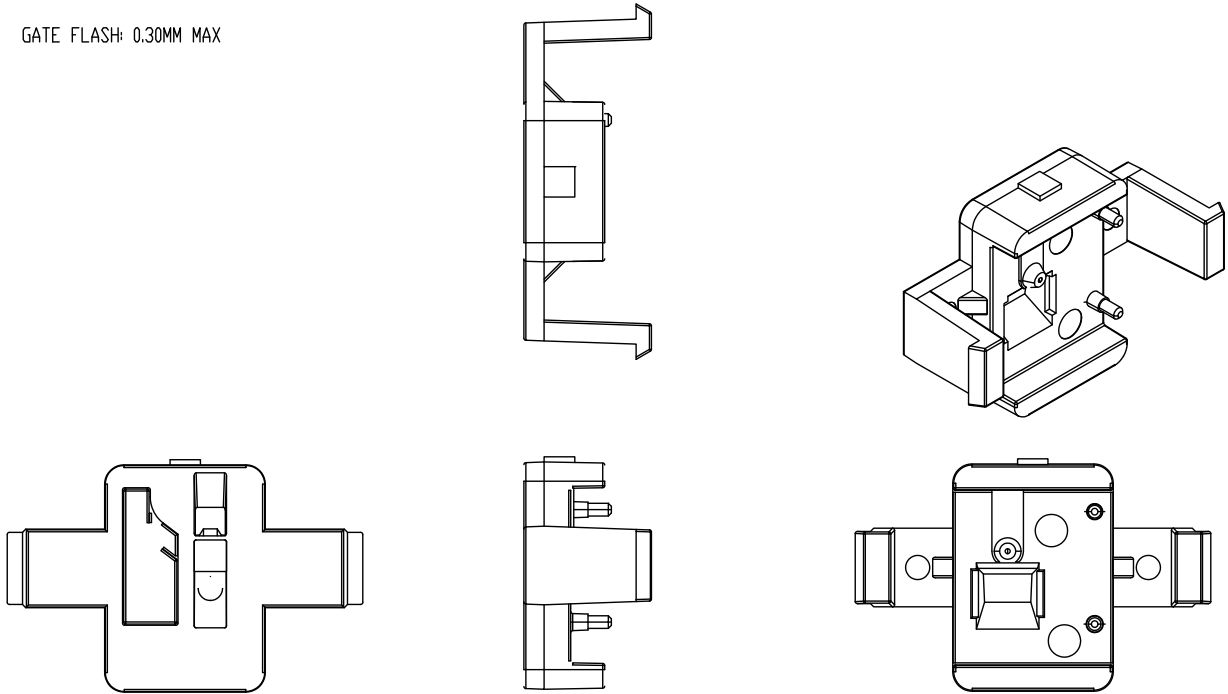
Figure 16. QFN Package



001-44934 *C

Figure 17. Lens

GATE FLASH: 0.30MM MAX



001-44677 *B

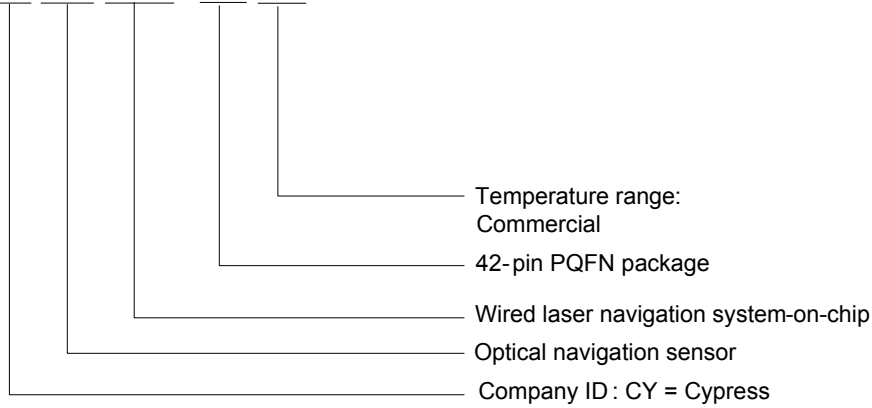
Ordering Information

The CYONS2000 and CYONSLENS2000 are sold separately. When placing orders, order both part numbers.

Part Number	Package	Application
CYONS2000-LBXC	42 pin PQFN	Desktop wired
CYONSLENS2000-C	Lens - 4 mm height	Molded optic

Ordering Code Definition

CYONS XXXX-XXX C



Document Conventions

Acronyms Used

Table 20 lists the acronyms used in this document.

Units of Measure

A units of measure table in Table 21 lists the abbreviations used to measure the devices.

Numeric Naming

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase 'h' (for example, '14h' or '3Ah'). Hexadecimal numbers may also be represented by a '0x' prefix, the C coding convention. Binary numbers have an appended lowercase 'b' (for example, '01010100b' or '01000011b'). Numbers not indicated by an 'h', 'b', or '0x' are decimal.

Table 20. Acronyms

Acronym	Description	Acronym	Description
AC	Alternating Current	LDO	Low Drop Out (regulator)
ADC	Analog to Digital Converter	LED	Light Emitting Diode
API	Application Programming Interface	LPC	Low Power Comparator
CDRH	Center for Devices and Radiological Health	LSb	Least-significant Bit
CPI	Counts per Inch	LVD	Low Voltage Detect
CPU	Central Processing Unit	M8C	Cypress' 8-bit CPU Core
DAC	Digital to Analog Converter	MCU	Microcontroller Unit
DC	Direct Current	MIPS	Million Instructions per Second
DSP	Digital Signal Processor	MSb	Most-significant Bit
ESD	Electrostatic Discharge	MUX	Multiplexer
GND	Ground	PC, PCB	Printed Circuit, Printed Circuit Board
GPIO	General Purpose I/O	PDIP	Plastic Dual In-Line Package
HEX	Hexadecimal	PGA	Programmable Gain Amplifier
High-Z	High Impedance	POR	Power On Reset
I ² C	Inter-Integrated Circuit (bus)	PQFN	Plastic Quad Flat No-Leads (package)
ICE	In-circuit Emulator	PSoC	Programmable System-on-Chip
IDAC	DAC-Controlled Current Source	PSRR	Power Supply Rejection Ratio
IDE	Integrated Development Environment	PWM	Pulse Width Modulator
IEC	International Electrotechnical Commission	QFN	Quad Flat No-Leads (package)
ILO	Internal Low Speed Oscillator	SoC	System on Chip
IMO	Internal Main Oscillator	SPI	Serial Peripheral Interface (bus)
I/O	Input/Output	SRAM	Static Random Access Memory
JEDEC	Joint Electron Devices Engineering Council	USB	Universal Serial Bus
LCD	Liquid Crystal Display	VCSEL	Vertical Cavity Surface Emitting Laser

Table 21. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
°C	degree Celsius	μV	microvolts
g	acceleration of gravity	mA	milliampere
KB	1024 bytes	ms	millisecond
in/s	inches per second	mV	millivolt
kHz	kilohertz	nH	nanohenry
kΩ	kilohm	nm	nanometer
kV	kilovolt	ns	nanosecond
MHz	megahertz	Ω	ohm
μA	microampere	pF	picofarad
μF	microfarad	pp	peak-to-peak
μH	microhenry	V	volt
μs	microsecond	W	watt

Document History Page

Document Title: CYONS2000 OvationONS™ II Wired Laser Navigation System-on-Chip Document Number: 001-44044				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	2261927	FJZ	See ECN	New datasheet.
*A	2580125	FJZ/PYRS	10/07/08	Extensive Updates
*B	2769396	FJZ/AESA	25/09/09	Updated Getting Started and Development Tools sections. Updated thermal impedance, wireless kit part number, Flash specs, storage temperature, I2C footnote, pin table, and c compiler information.
*C	2889331	FJZ	03/09/10	Added Table of Contents. Updated package diagram and sales links.
*D	2903558	FJZ	04/20/10	Update LVD, USB, SPI Master and SPI Slave specs. Numerous minor updates for improved clarity and consistency.
*E	2936335	MMCY	05/24/2010	Updated content to match the new template and style guide. No technical updates.
*F	3092209	FJZ	11/22/2010	Corrected error in Pin Description . Removed invalid reference to application note in Registration Assistance .
*G	3126503	FJZ	01/03/2011	Updated Figure 17 . Changed posting to external web

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